| | | | | | | | | <u> </u> | | | <u> </u> | | | | |
|---|--|--------------------|-----|-----|-----|----|----|----------|---------------|---------------------------------------|--------------|------------|---|--|--|
| FORM PTO-1449 (Modified) | | | | | | | | | | ATTY. DOCK | ET NO. | SERIAL N | SERIAL NO. The Brace Assigned. 10/632,622 | | |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT | | | | | | | | | | 030873/2889P | | 10/63: | | | |
| | | | | | | | | | | APPLICANT: | | | | | |
| | | | | | | | | | | Vikram SHROWTY and Santhanakris RAMAN | | | | | |
| (Use several sheets if necessary) | | | | | | | | | | FILING DATE | 07/31/2003 | GROUP: | GROUP: 2825 | | |
| REFERENCE | DES | SIC | SN/ | ΑT | 101 | ٧ | | | U.S. PA | TENT DOCUME | ENTS | | | | |
| EXAMINER INITIALS | | DOCUMENT NUMBER | | | | | | • | DATE | NAME | CLASS | SUBCLASS | FILING DATE (IF APPRO.) | | |
| W | | 6 | 0 | 9 | 3 | 2 | 1 | 4 | 07/25/00 | Dillon | 716 | 17 | | | |
| W> | | 6 | 4 | 4 | 6 | 2 | 4 | 8 | 09/03/02 | Solomon et al. | 716 | 17 | | | |
| | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | |
| | • | | | | | | | | FOREIGN PA | TENT DOCUM | ENTS | | | | |
| | | DOCUMENT NUMBER | | | | | | | DATE | COUNTRY | CLASS | SUBCLASS | Translation | | |
| | | | | | | | | | | · · · · · · · · · · · · · · · · · · · | | | | | |
| | L | <u> </u> | L | | | | | Ц | | | | | 1 | | |
| | | | 01 | ГΗΙ | ER | AI | RТ | (In | cluding Autho | or, Title, Date, I | Pertinent Pa | ges, etc.) | · | | |
| (V) | Liu, George Y. et al., "Chip-Level CMP Modeling and Smart Dummy for HDP and Conformal CVD Films," CMP-MIC Conference, February 11-12, 1999, pp. 120-127. | | | | | | | | | | | | | | |
| EXAMINER | | | | | | | | | | | | | | | |

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance <u>and</u> not considered. Include copy of this form with next communication to applicant.